

SR10-SCHX3

MIL-STD-810G 19" RACKMOUNT FANLESS
COMPUTER WITH INTEL® CORE i7- 8700T



- MIL-STD 810G COMPLIANCE
- 8TH GENERATION INTEL® CORE™ i7-8700T COFFEELAKE PROCESSOR
- UP TO 16GB DDR4 RAM
- MULTI DISPLAY WITH DISPLAYPORT, HDMI & DVI
- 1 x 2.5" SSD
- 2 x INTEL® GIGABIT ETHERNET
- 6 x USB PORTS, 3 x COM PORT
- 12V TO 24V DC-IN
- EXTENDED TEMPERATURE -20 TO 60 °C



Extended
Temperature
+60°C
-20°C

SPECIFICATIONS

| SPECIFICATIONS | |
|----------------------------|---|
| High Performance Processor | Intel® 8th Gen Core™ i7-8700T (Frequency 2.4GHz, Turbo Boost Frequency up to 4.0GHz), 6-Core, 12 Thread Support, 12MB SmartCache. Build-in UHD Graphics 630 for excellent 3D, Turbo Boost Technology 2.0, VPro and Hyper-Threading support |
| Memory | Up to 16GB DDR4 RAM |
| Chipset | Q370 |
| DISPLAY | |
| GPU | Intel® UHD Graphics 630 |
| Display Port | Resolution up to 4096x2304@60Hz |
| HDMI | Resolution up to 4096x2160@30Hz |
| DVI-D | Resolution up to 1920x1200 @ 60Hz |
| STORAGE | |
| Storage Device | 1 x 2.5" Solid State Disk (SSD) 1 x mSATA Rugged Industrial NAND Flash mSATA Storage w/ Rugged -40/+85C High Capacity, optional Pre-loaded with Linux or Windows OS. 64 / 128 / 256 / 512GB / 1TB / 2TB Innodisk 3MG2-P Series MLC SATA III 6Gb/s Flash SSD, Rated for 520 MB/sec Sequential Read ; 350 MB/sec Write Max. |
| ETHERNET | |
| Ethernet | 2 x Intel Gigabit Ethernet LAN Interfaces (10/100/1000Mbps) |
| REAR I/O | |
| DisplayPort | 1 x 20Pin DisplayPort connector (Female) |
| HDMI | 1 x 19Pin HDMI connector (Female) |
| DVI-D | 1 x 20Pin DVI-D connector (Female) |
| Ethernet | 2 x RJ45 Gigabit Ethernet LAN Interfaces |
| Serial Port | 1 x DB9 connector (RS-232) |
| USB Port | 4 x USB3.1 Gen2 standard-A connectors |
| Audio Port | 1 x Line-Out, 1 x MIC-In connector |
| DC-IN | 4P Rugged Terminal connector |
| FRONT I/O | |
| Button | 1 x Power Button w/Indicator LED |
| Indicator LED | 1 x HDD LED |
| USB Port | 2 x USB2.0 standard-A connectors |
| Serial Port | 2 x DB9 connectors (1 x RS-232, 1 x RS232/422/485) |

APPLICATIONS, OPERATING SYSTEM

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| Applications | Commercial and Military Platforms Requiring Compliance to MIL-STD-810G Embedded Computing, Process Control, Intelligent Automation and manufacturing applications where Harsh Temperature, Shock, Vibration, Altitude, Dust and EMI Conditions. Used in all aspects of the military. |
| Operating System | Windows 10 64bit Ubuntu16.04, Ubuntu14.04, Fedora 28 |

PHYSICAL

| | |
|-----------------------|--|
| Dimension (W x D x H) | 308 x 149 x 65.2mm |
| Weight | 3.21Kg |
| Chassis | Aluminum Alloy, Corrosion Resistant. |
| Finish | Anodic aluminum oxide (Color Iron gray) |
| Cooling | Natural Passive Convection/Conduction. No Moving Parts |
| Connectors | DC-IN : PHOENIX CONTACT 1776715 RJ45 Ethernet : RTB-19GB9J1A COM: FEN YING SM10-09P DVI : FOXCONN QH11121-DA4E-4F HDMI + DP : JKCR Display and HDMI Female |
| Ingress Protection | Dust Proof (Similar to IP50) |

ENVIRONMENTAL

| | |
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| MIL-STD-810G Test | Method 507.5, Procedure II (Temperature & Humidity) Method 516.6 Shock-Procedure V Non-Operating (Mechanical Shock) Method 516.6 Shock-Procedure I Operating (Mechanical Shock) Method 514.6 Vibration Category 24/Non-Operating (Category 20 & 24, Vibration) Method 514.6 Vibration Category 20/Operating (Category 20 & 24, Vibration) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I (Temperature shock) |
| Operating Temperature | -20 to 60°C (ambient with 0.7m/s airflow) |
| Storage Temperature | -40 to 85°C |
| EMC | CE and FCC compliance |

ORDERING INFORMATION

SR10-SCHX3

**MIL-STD-810G 19" RACKMOUNT FANLESS COMPUTER WITH
INTEL® CORE I7- 8700T, 1 x DP, 1 x HDMI, 1 x DVI, 6 x USB,
12V TO 24V DC-IN**

DIMENSION

